TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

TPCF8001

Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance: RDS (ON) = $19 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 8 S (typ.)$
- Low leakage current: $IDSS = 10 \mu A (max) (VDS = 30 V)$
- Enhancement-model: $V_{th} = 1.3 \text{ to } 2.5 \text{ V}$

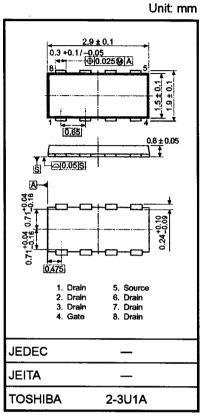
 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{mA})$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	30	٧
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	30	٧
Gate-source voltage		V _{GSS}	±20	٧
Drain current	DC (Note 1)	lD	7	
	Pulsed (Note 1)	IDP	28	A
Drain power dissipation	on (t = 5 s) (Note 2a)	PD	2.5	w
Drain power dissipati	on (t = 5 s) (Note 2b)	PD	0.7	w
Single pulse avalanch	ne energy (Note 3)	EAS	8	mJ
Avalanche current		IAR	3.5	Α
Repetitive avalanche	energy (Note 4)	EAR	0.25	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature	range	T _{stg}	-55~150	°C

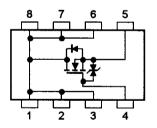
Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

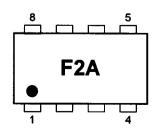


Weight: 0.011 g (typ.)

Circuit Configuration



Marking (Note 5)



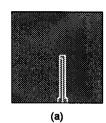
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R _{th (ch-a)}	50.0	*C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	178.6	°C/W

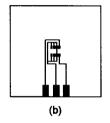
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



FR-4 25.4 × 25.4 × 0.8 Unit: (mm)



FR-4 25.4 × 25.4 × 0.8 Unit: (mm)

Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 0.5 mH, R_G = 25 Ω , I_{AR} = 3.5 A

Note 4: Repetitive rating: pulse width limited by Max. Channel temperature.

Note 5: Black round marking "•" locates on the left lower side of parts number "F3A" indicates terminal No.1.

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Symbol Test Condition		Тур.	Max	Unit
Gate leakage cur	rent	IGSS	V _{GS} = ±16 V, V _{DS} = 0 V		_	±10	μА
Drain cut-off curr	ent	IDSS	V _{DS} = 30 V, V _{GS} = 0 V		_	10	μА
Drain-source breakdown voltage		V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30			٧
		V (BR) DSX	I _D = 10 mA, V _{GS} = -20 V	15	_	-	
Gate threshold ve	threshold voltage		V _{DS} = 10 V, I _D = 1mA	1.3		2.5	٧
Drain-source ON resistance		_	V _{GS} = 4.5 V, I _D = 3.5 A		24	31	mΩ
		RDS (ON)	V _{GS} = 10 V, I _D = 3.5 A	_	19	23	
Forward transfer	orward transfer admittance		V _{DS} = 10 V, I _D = 3.5A	4	8	_	S
Input capacitance		C _{iss}		_	1270		pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	150	_	
Output capacitance		Coss]	_	190		
	Rise time	t _r	V _{GS} 10 V	_	3.8	_	ns
Consider him on Aires o	Turn-on time	ton] -65 ₀ v J L . [• 0	_	9.4	_	
Switching time	Fall time	tr	7.7.7.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0	_	8.4		
	Turn-off time	^t off	V _{DD} ≃ 15 V Duty ≦ 1%, t _w = 10 μs		40	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 24 V, V _{GS} = 10 V,	_	25.4	_	nC
Gate-source charge		Q _{gs}	$\log 24 \text{ V, VGS} = 10 \text{ V,}$ $\log 7.0 \text{ A}$	_	3.6	_	
Gate-drain ("miller") charge		Q _{gd}		_	6.2	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Charact	Characteristics Symbol		Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	IDRP	<u> </u>	_	_	28	Α
Forward voltage	(diode)	V _{DSF}	I _{DR} = 7.0 A, V _{GS} = 0 V	_	_	-1.2	V

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